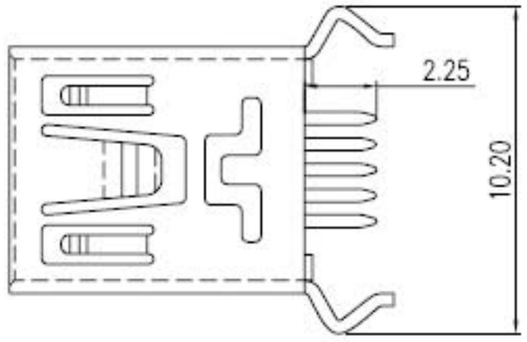
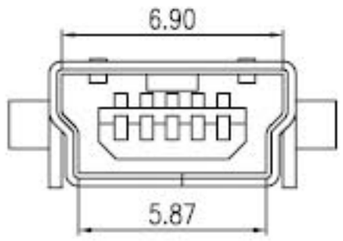
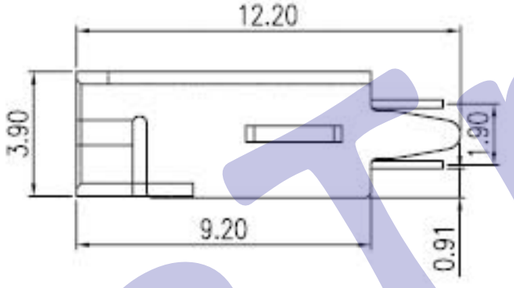
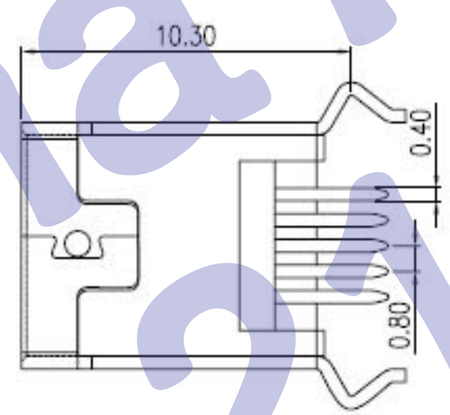
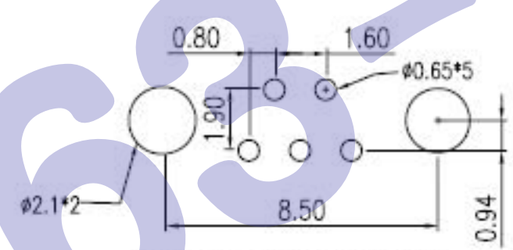
REV.	ECN NO.	DESCRIPTION	DRWN	APPD.	DATE











RECOMMENDED PCB LAYOUT

特性:Specifications:
电器:Electrical:
接触阻抗:Contact Resistance
50 milliohms MAX
耐电压:Dielectric Withstanding Voltage:
100 V AC AT Sea LevoL
绝缘阻抗:Insulation Resistance:
100 MEGA ohms MIN

材料:Matorial:
塑胶:Housing:Hing Temperature Thermoplastics,
UL 94V-0 耐高温塑胶
端子:Contact: Copper Alloy 铜合金
铁壳:Shell: Copper Alloy 铜合金

电镀:Finish:
端子:Contact: Piated Gold in Mating Area;
Tin On Solder Talls
接触点镀金.脚镀锡

铁壳:Shell:
Nickel/ Plating 镀镍

UNITS mm	SCALE 1:1	REV. A0	SHEET 1 OF 1	HDC 有限公司	
		DATE 2006-05-30		TITLE MINI USB 5F 180° 母座	
GENERAL TOLERANCE 0. ±0.30 0.0 ±0.20 0.00 ±0.13 0.° ±2° 0.0° ±1°		DR. Zhan yun ping			
		CHK. TONY		MAT'L SEE NOTES	FINISH SEE NOTES
		APPD. YXL	DWG.NO.	A	PART NO. GUSB-B-012 / SIZE A4

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